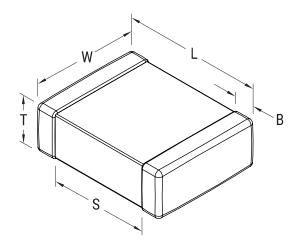


C0603X569B2TAC7411

SMD Comm X8G HT150C Flex, Ceramic, 5.6 pF, +/-0.1 pF, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 0603, 0.4 mm



Click here for the 3D model.

General Information	
Series	SMD Comm X8G HT150C Flex
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	4.6 mg
Shelf Life	78 Weeks
MSL	1

5.6 pF
1 MHz 1.0Vrms
+/-0.1 pF
200 VDC
500 VDC
-55/+150°C
X8G
30 ppm/C, 1MegaHz 1.0Vrms
0.1% 1 MHz 1.0Vrms
0% Loss/Decade Hour: Referee Time is 1000 Hours
100 GOhms

 Dimensions

 Chip Size
 0603

 L
 1.6mm +/-0.17mm

 W
 0.8mm +/-0.15mm

 T
 0.8mm +/-0.15mm

 S
 0.4mm MIN

 B
 0.45mm +/-0.15mm

Packaging Specifications Packaging Temperature Packaging Quantity 15

T&R, 330mm, Paper Tape 15000

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